

# 欧智通科技

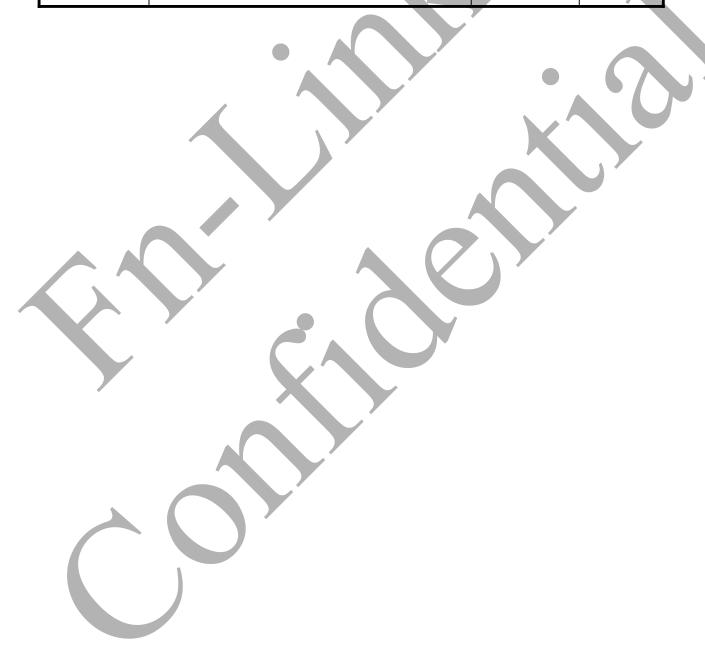
Fn-Link 6223A-SRD

WiFi Single-band 1X1 +
Bluetooth v2.1+EDR/Bluetooth
3.0/3.0+HS/4.0

**Module Datasheet** 

# **Revision History**

Date	Revision Content	Revised By	Version
2016-9-26	First Released	William Tan	V1.0
	<b>A</b> 1		





# Contents

Cc	ontents	3
1.	Introduction	4
2.	Features	5
3.	General Specification	5
	3.1 General Specification	
	3.1.2 Recommended Operating Rating	5
4.	WiFi/BT RF Specification	5
	4 .1 2.4GHz RF Specification	5
5.	Power Consumption	8
6.	Pin Assignments	9
	6.1 Pin Outline	9
	6.2 Pin Definition	9
7.	Dimensions	. 11
	7.1 Outline Drawing	., 11
	7.2 PCB LAYOUT Reference	11
8.	Host Interface Timing Diagram	11
	8.1 SDIO Pin Description	11
	8.2 SDIO Default Mode Timing Diagram	12
	8.3 SDIO High Speed Mode Timing Diagram	13
	8.4 SDIO Bus Timing Specifications in SDR Modes	
	8.5 SDIO Bus Timing Specifications in DDR50 Mode	
9.	Reference Design	
	. Recommended Reflow Profile	19
	. Package错误! 未定义书	签。



#### 1. Introduction

6223A-SRD is a small size and low profile of WiFi + BT Combo module with LGA (Land-Grid Array) footprint, board size is 12mm\*12mm with module thickness of 2mm. It can be easily manufactured on SMT process and highly suitable for tablet PC, ultra book, mobile device and consumer products. It provides SDIO interface for WiFi to connect with host processor and high speed UART interface for BT. It also has a PCM interface for audio data transmission with direct link to external audio codec via BT controller. The WiFi throughput can go up to 150Mbps in theory by using 1x1 802.11n b/g/n MIMO technology and Bluetooth can support BT2.1+EDR/BT3.0 and BT4.0.

6223A-SRD uses highly integrated WiFi/BT single chip based on advanced COMS process. 6223A-SRD integrates whole WiFi/BT function blocks into a chip, such as SDIO/UART, MAC, BB, AFE, RFE, PA, EEPROM and LDO/SWR, except fewer passive components remained on PCB.

This compact module is a total solution for a combination of Wi-Fi + BT technologies. The module is specifically developed for Smart phones and Portable devices.





#### 2.Features

- Operate at ISM frequency bands (2.4GHz)
- SDIO for WiFi and UART for Bluetooth
- IEEE standards support: IEEE 802.11b, IEEE 802.11g, IEEE 802.11n, IEEE 802.11d, IEEE 802.11e, IEEE 802.11h, IEEE 802.11i
- Fully Qualified for Bluetooth 2.1+EDR specification including both 2Mbps and 3Mbps modulation mode
- Fully qualified for Bluetooth 3.0
- Fully qualified for Bluetooth 4.0 Dual mode
- Full-speed Bluetooth operation with Piconet and Scatternet support
- Enterprise level security which can apply WPA/WPA2 certification for WiFi.
- WiFi 1 transmitter and 1 receiver allow data rates supporting up to 150 Mbps downstream and 150 Mbps upstream PHY rates

# 3. General Specification

#### 3.1 General Specification

Model Name	6223A-SRD
Product Description	Support WiFi/Bluetooth functionalities
Dimension	L x W x H: 12 x 12 x1.7 (typical) mm
WiFi Interface	Support SDIO V3.0
BT Interface	UART / PCM
Operating temperature	0°C to 70°C
Storage temperature	-40°C to 85°C

#### 3.1.2 Recommended Operating Rating

	Min.	Тур.	Max.	Unit
Operating Temperature	0	25	70	deg.C



VCC33	3.15	3.3	3.45	V
VDDIO	1.7	1.8 or 3.3	3.45	V

# 4.WiFi/BT RF Specification

#### 4.1 2.4GHz RF Specification

Feature	Description
Operating	2.400~2.4835GHz
Frequency	
Standards	WiFi:
	IEEE 802.11b, IEEE 802.11g, IEEE 802.11n, IEEE
	802.11d, IEEE 802.11e, IEEE 802.11h, IEEE 802.11i
	BT:
	V2.1+EDR/BT v3.0/BT v3.0+HS/BT v4.0
Modulation	WiFi:
	802.11b: CCK(11, 5.5Mbps), QPSK(2Mbps),
	BPSK(1Mbps),
	802.11 g/n: OFDM
	BT:
	8DPSK, π /4 DQPSK, GFSK
PHY Data rates	WiFi:
	802.11b: 11,5.5,2,1 Mbps
	802.11g: 54,48,36,24,18,12,9,6 Mbps
	802.11n: up to 150Mbps
	BT:
	1 Mbps for Basic Rate
	2,3 Mbps for Enhanced Data Rate
Transmit Output	WiFi:
Power	802.11b@11Mbps 16±1.5dBm
	<b>802.11g@54Mbps 14</b> ±1.5 <b>dBm</b>
	802.11n@65Mbps 13±1.5dBm (MCS 7_HT20)



	UZZJA-		
	13±1.5dBm (MCS 7_HT40)		
	BT:		
	Max +10dBm		
EVM	802.11b /1Mbps : EVM≦-10dB		
	802.11b /11Mbps : EVM ≦ -10dB		
	802.11g /6Mbps : EVM ≦ -5dB		
	802.11g /54Mbps : EVM≦-25dB		
	802.11n /6.5Mbps : EVM≦-5dB		
	802.11n /65Mbps : EVM≦-28dB		
	802.11n /13.5Mbps : EVM ≦ -5dB		
	802.11n /135Mbps : EVM ≦ -28dB		
Receiver Sensitivity	802.11b@8% PER		
(WiFi)	1Mbps ≦-91dBm		
	2Mbps≦ -89dBm		
	<b>5.5Mbps</b> ≤ <b>-87dBm</b>		
	11Mbps ≦-85dBm Max input level>-8		
	802.11g@10% PER		
	6Mbps ≦-87dBm		
	9Mbps ≦-86dBm		
12Mbps≦ -84dBm			
	18Mbps≦ -82dBm		
	24Mbps≦ -79dBm		
	36Mbps ≦ -75dBm		
	48Mbps ≦-71dBm		
	<b>54Mbps</b> ≦ <b>-70dBm</b> Max input level ≥ -20		
	802.11n@10% PER		
	<b>HT20_MCS</b> 0 <b>≦-87dBm</b> HT40_MCS 0 <b>≤</b> -84		
	HT20_MCS 1 ≦ -84dBm HT40_MCS 1 ≦ -81		
	HT20_MCS 2 ≦-82dBm HT40_MCS 2≦-79		
	HT20_MCS 3 ≤-79dBm HT40_MCS 3≤-76		
	HT20_MCS 4 ≦-75dBm HT40_MCS 4≦-72		
	HT20_MCS 5 ≤-71dBm HT40_MCS 5≤-68		
	HT20_MCS 6 ≤-70dBm		
	HT20_MCS 7 ≤ -69dBm HT40_MCS 7≤ -66		
	Max input level ≥-20		
Receiver Sensitivity	-89dBm @ 1Mbps		
(BT)	-86dBm @ 2Mbps		
	-83dBm @ 3Mbps		
Operating Channel	WiFi 2.4GHz:		



	11: (Ch. 1-11) – United States
	13: (Ch. 1-13) – Europe
	14: (Ch. 1-14) – Japan
	BT 2.4GHz: <b>Ch. 0 ~78</b>
Media Access	WiFi: CSMA/CA with ACK
Control	BT: AFH, Time Division
Antenna	External Antenna
Network Architecture	WiFi: Ad-hoc mode (Peer-to-Peer )
	Infrastructure mode
	Software AP
	WiFi Direct
	BT: Pico Net, Scatter Net
Security	WiFi: WPA, WPA-PSK, WPA2, WPA2-PSK, WEP 64bit &
	128bit, IEEE 802.11x, IEEE 802.11i
	BT: Simple Paring
OS Supported	Android /Linux/ Win CE /iOS /XP/WIN7
Host Interface	WiFi: SDIO
	BT: UART
Operating Voltage	3.3±10% Vdc I/O supply voltage
Dimension	Typical L12.0*W12.0*H1.7mm

# 5. Power Consumption

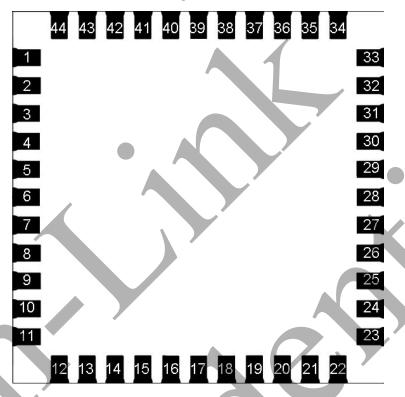
Power Consumption	WiFi only:
(Typical by using	TX Mode: (Throughput mode) 170mA (MCS7/BW40/13dBm)
SWR)	RX Mode: (Throughput mode) 130mA (MCS7/BW40/-60dBm)
	Associated Idle power saving with DTIM=3 2.1mA
	Unassociated Idle: 0.1mA
	RF disable Mode: 0.1mA
	BT: Inquiry & Page Scan: 0.9 mA
	ACL no traffic: 7.5mA
	SCO HV3: 15.0mA



# 6. Pin Assignments

#### 6.1 Pin Outline





#### 6.2 Pin Definition

Pin#	Name	Description
1	GND	Ground connection
2	WL_BT_ANT	RF I/O port
3	GND	Ground connection
4	NC	Floating (NC)
5	NC	Floating (NC)
6	BT_WAKE	Wake-up BT
7	BT_HOST_WAKE	BT wake-up BT
8	NC	Floating (NC)
9	VBAT	3.3±10% V Main power voltage source input
10	WL_XTAL_IN	Floating (NC)
11	WL_XTAL_OUT	Floating (NC)
12	WL_REG_ON	Internal regulators power enable/disable
13	WL_HOST_WAKE	WLAN wake-up HOST
14	SDIO_DATA_2	SDIO data line 2



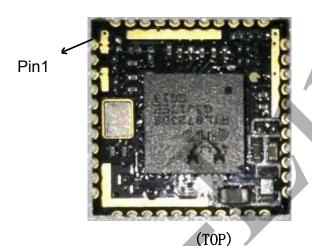


-		
15	SDIO_DATA_3	SDIO data line 3
16	SDIO_DATA_CMD	SDIO command line
17	SDIO_DATA_CLK	SDIO clock line
18	SDIO_DATA_0	SDIO data line 0
19	SDIO_DATA_1	SDIO data line 1
20	GND	Ground
21	VIN_LDO_OUT	Floating(NC)
22	VDDIO	I/O Voltage supply input
23	VIN_LDO	Floating (NC)
24	LPO	External Clock input(32.768kHz), need to be
25	PCM_OUT	PCM Output
26	PCM_CLK	PCM Clock
27	PCM_IN	PCM Input
28	PCM_SYNC	PCM Sync
29	WL_VDD_TXCO	Floating (NC)
30	TCXO_IN	Floating (NC)
31	GND	Ground
32	NC	Floating (NC)
33	GND	Ground
34	BT_RST_N	BT Reset IN
35	NC	Floating (NC)
36	GND	Ground
37	BT_XTAL_IN	Floating (NC)
38	BT_XTAL_OUT	Floating (NC)
39	NC	Floating (NC)
40	NC	Floating (NC)
41	UART_RTS_N	UART RTS
42	UART_TXD	UART Output
43	UART_RXD	UART Input
44	UART_CTS_N	UART CTS
45~47	TP1~TP3	Test point1~3 Floating (NC)
Total	47PINS	12.0*12.0*1.7mm LGA Package



## 7. Dimensions

## 7.1 Outline Drawing



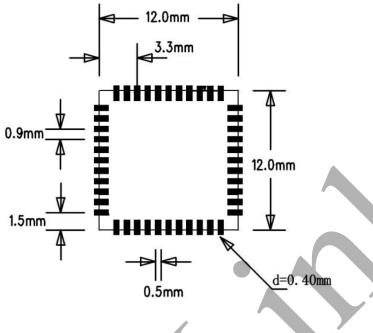
PEDSSM23

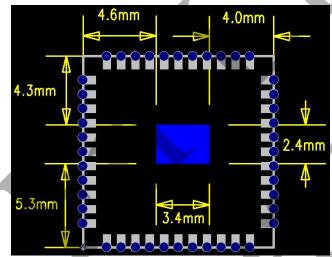
(BOTTOM)

Note of silkscreen: "F23DSSM23" is our internal P/N "2016.05.11" is date of PCB

7.2 PCB LAYOUT Reference







# 8. Host Interface Timing Diagram

#### 8.1 SDIO Pin Description

The module supports SDIO version 3.0 for all 1.8V 4-bit UHSI speeds: SDR50(100 Mbps), and DDR50(50MHz, dual rates) in addition to the 3.3V default speed(25MHz) and high speed (50 MHz). It has the ability to stop the SDIO clock and map the interrupt signal into a GPIO pin. This 'out-of-band' interrupt signal notifies the host when the WLAN device wants

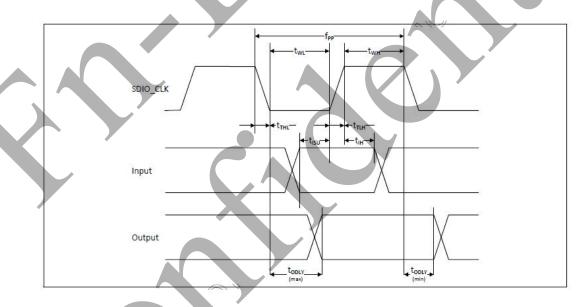


to turn on the SDIO interface. The ability to force the control of the gated clocks from within the WLAN chip is also provided.

SDIO Pin Description

SD 4-Bit Mode		
DATA0	Data Line 0	
DATA1	Data Line 1 or Interrupt	
DATA2	Data Line 2 or Read Wait	
DATA3	Data Line 3	
CLK	Clock	
CMD	Command Line	

## 8.2 SDIO Default Mode Timing Diagram

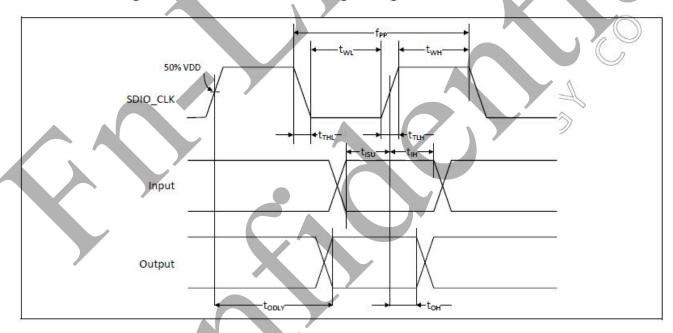




Parameter	Symbol	Minimum	Typical	Maximum	Unit
SDIO CLK (All values are referred to minimu	m VIH and ma	ximum VIL <sup>b</sup> )			
Frequency – Data Transfer mode	fPP	0	<b>6</b> 4	25	MHz
Frequency – Identification mode	fOD	0	-	400	kHz
Clock low time	tWL	10	24		ns
Clock high time	tWH	10	=	-	ns
Clock rise time	tTLH	7.3	-8	10	ns
Clock low time	tTHL	-	-	10	ns
Inputs: CMD, DAT (referenced to CLK)					
Input setup time	tISU	5	(50)	150	ns 🔾
Input hold time	tIH	5	No.	(HES)	ns )
Outputs: CMD, DAT (referenced to CLK)				• 1	
Output delay time – Data Transfer mode	tODLY	0	-	14	ns
Output delay time – Identification mode	tODLY	0	9,	50 🕥	ns

a. Timing is based on CL  $\leq$  40pF load on CMD and Data. b. min(Vih) = 0.7  $\times$  VDDIO and max(Vil) = 0.2  $\times$  VDDIO.

## 8.3 SDIO High Speed Mode Timing Diagram



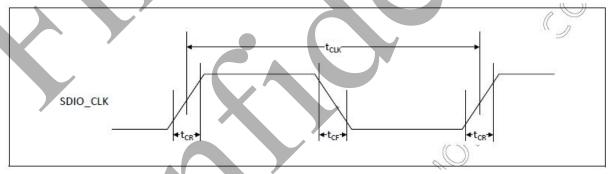


Parameter	Symbol	Minimum	Typical	Maximum	Unit
SDIO CLK (all values are referred to min	imum VIH and mo	aximum VIL <sup>b</sup> )			
Frequency – Data Transfer Mode	(SfPP	0	<u> </u>	50	MHz
Frequency – Identification Mode	fOD	0	<u></u>	400	kHz
Clock low time	⇒ tWL	7	=	<del>13</del> 1	ns
Clock high time	tWH	7	=	=	ns
Clock rise time	tTLH	-	<u>=</u> 1	3	ns
Clock low time	tTHL	<del></del>	<del></del>	3	ns
Inputs: CMD, DAT (referenced to CLK)					
Input setup Time	tISU	6	-	<del></del>	ns
Input hold Time	tIH	2	-	<u>2-</u> 2	ns
Outputs: CMD, DAT (referenced to CLK)					
Output delay time – Data Transfer Mode	tODLY	-	(55)	14	ns
Output hold time	tOH	2.5	=	=	ns
Total system capacitance (each line)	CL	<del>=</del> 1		40	pF

a Timing is based on  $CL \le 40$  pF load on CMD and Data. b. min(Vih) = 0.7 × VDDIO and max(Vil) = 0.2 × VDDIO.

#### 8.4 SDIO Bus Timing Specifications in SDR Modes

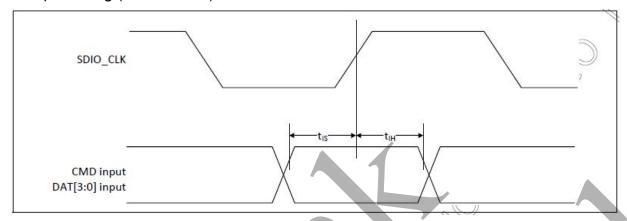
#### Clock timing(SDR Modes)



Parameter	Symbol	Minimum	Maximum	Unit	Comments
_	t <sub>CLK</sub>	40	-	ns	SDR12 mode
		20	-	ns	SDR25 mode
	,	10	- 4	ns	SDR50 mode
		4.8	- (	√ns	SDR104 mode
-	t <sub>CR</sub> , t <sub>CF</sub>	<del>53</del> 6	0.2 × tolk	ns	$t_{CR}$ , $t_{CF}$ < 2.00 ns (max) @100 MHz, $C_{CARD}$ = 10 pF
		į			$t_{CR}, t_{CF}$ < 0.96 ns (max) @208 MHz, $t_{CARD}$ = 10 pF
Clock duty	12-	30	70	%	92



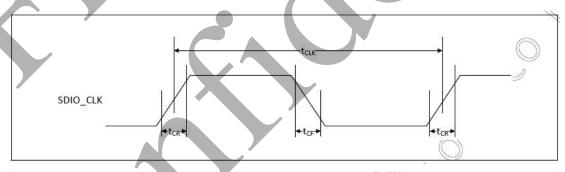
#### Card Input timing (SDR Modes)



Symbol	Minimum	Maximum	Unit	Comments	
SDR104 Md	ode		_ ^ _		
t <sub>IS</sub>	1.70 <sup>a</sup>	_	ns	C <sub>CARD</sub> = 10 pF, VCT = 0.975V	
t <sub>IH</sub>	0.80	1-	ns	C <sub>CARD</sub> = 5 pF, VCT = 0.975V	
SDR50 Mod	de		1		
t <sub>IS</sub>	3.00	-	ns	C <sub>CARD</sub> = 10 pF, VCT = 0.975V	
t <sub>IH</sub>	0.80	-	ns	C <sub>CARD</sub> = 5 pF, VCT = 0.975V	

a. SDIO 3.0 specification value is 1.40 ns.

## 8.5 SDIO Bus Timing Specifications in DDR50 Mode

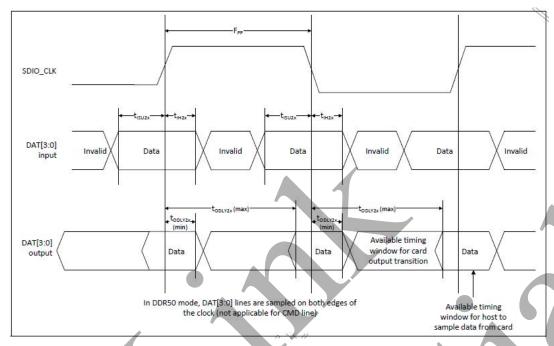


Parameter	Symbol	Minimum	Maximum	Unit	Comments
	t <sub>CLK</sub>	20	<del></del> 1	ns	DDR50 mode
	t <sub>CR</sub> ,t <sub>CF</sub>	7	0.2 × tCLK	ns	t <sub>CR</sub> , t <sub>CF</sub> < 4.00 ns (max) @50 MHz, C <sub>CARD</sub> = 10 pF
Clock duty	-	45	55	% (	E

**Data Timing** 



#### 6223A-SRD

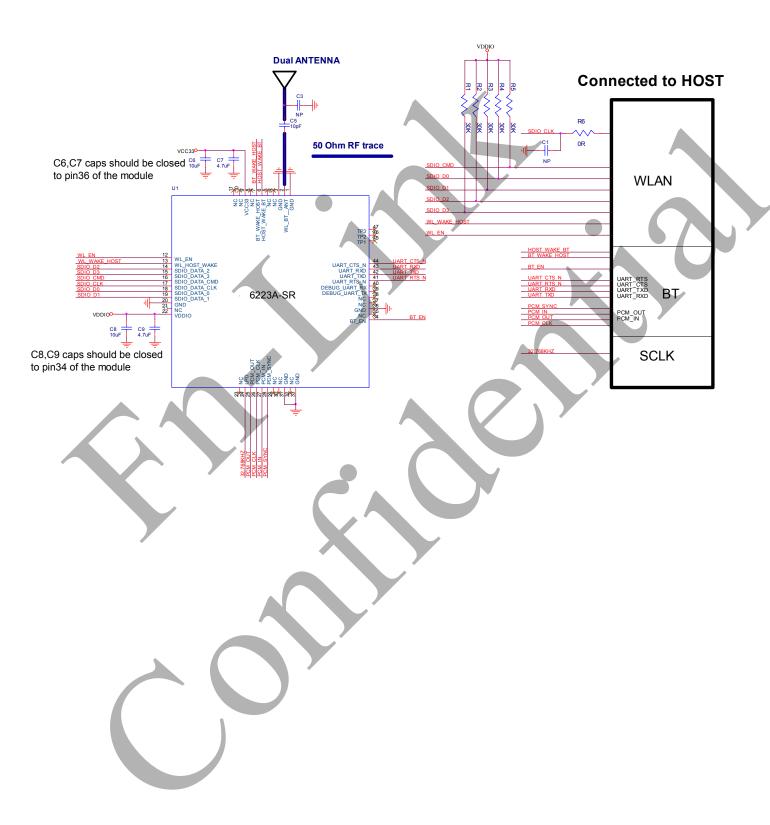


Parameter	Symbol	Minimum	Maximum	Unit	Comments
Input CMD		0			
Input setup time	t <sub>ISU</sub>	6	<u> </u>	ns	C <sub>CARD</sub> < 10pF (1 Card)
Input hold time	t <sub>IH</sub>	0.8		ns	C <sub>CARD</sub> < 10pF (1 Card)
Output CMD	N. N.				
Output delay time	t <sub>ODLY</sub>	<del>10</del> %	13.7	ns	C <sub>CARD</sub> < 30pF (1 Card)
Output hold time	ton	1.5	-	ns	C <sub>CARD</sub> < 15pF (1 Card)
Input DAT	3/1			K	
Input setup time	t <sub>ISU2x</sub>	3		ns	C <sub>CARD</sub> < 10pF (1 Card)
Input hold time	t <sub>IH2x</sub>	0.8	-	ns	C <sub>CARD</sub> < 10pF (1 Card)
Output DAT				7	
Output delay time	t <sub>ODLY2x</sub>		7.85 <sup>a</sup>	ns	C <sub>CARD</sub> < 25pF (1 Card)
Output hold time	t <sub>ODLY2x</sub>	1.5		ns	C <sub>CARD</sub> < 15pF (1 Card)

a SDIO 3.0 specification value is 7.0 ns.



# 9. Reference Design

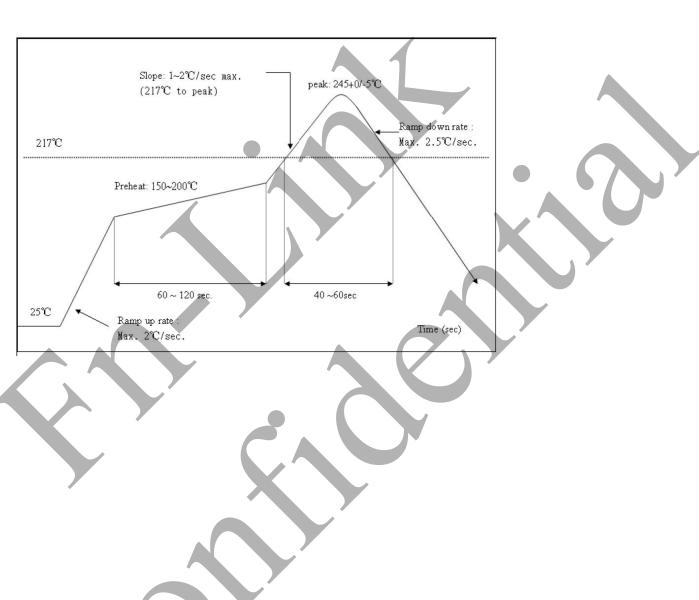




## 10. Recommended Reflow Profile

Referred to IPC/JEDEC standard.

Peak Temperature : <250°C Number of Times : ≤2 times





# 11.Package

the take-up package



Using self-adhesive tape

Size of black tape:24mm\*32.6m the cover tape :2.13mmm\*32.6m

Color of plastic disc:blue

A roll of 2000pcs



NY bag size:460mm\*385mm



size: 350\*350\*35mm







The packing case size:350\*210\*370mm